Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.
If you would find description “Panasonic” or “Panasonic semiconductor solutions”, please replace it with NTCJ.

※ Except below description page
“Request for your special attention and precautions in using the technical information and semiconductors described in this book”

Nuvoton Technology Corporation Japan

Panasonic

FK3303010L

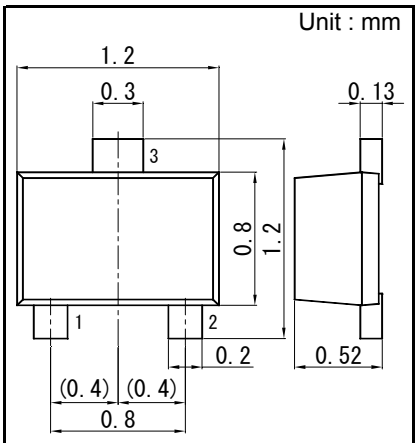
Silicon N-channel MOS FET

For switching
FK350301 in SSSMini3 type package

■ Features
- Low drive voltage: 2.5 V drive
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol X1

■ Packaging
Embossed type (Thermo-compression sealing): 10 000 pcs / reel (standard)



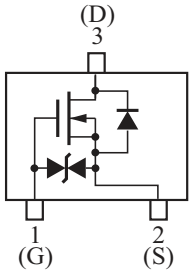
1. Gate
2. Source
3. Drain

Panasonic	SSSMini3-F2-B
JEITA	SC-105AA
Code	SOT-723

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Drain-source voltage	VDSS	30	V
Gate-source voltage	VGSS	±12	V
Drain current	ID	100	mA
Pulse drain current	IDp	200	mA
Total power dissipation	PD	100	mW
Channel temperature	Tch	150	°C
Operating ambient temperature	Topr	-40 to + 85	°C
Storage temperature	Tstg	-55 to +150	°C

Internal Connection



Pin Name

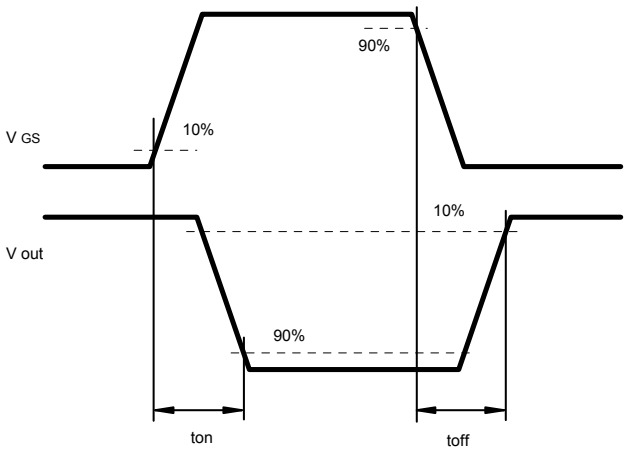
1. Gate
2. Source
3. Drain

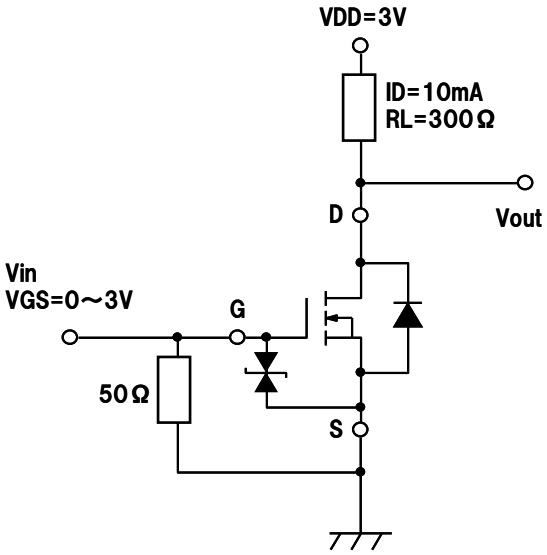
Established : 2010-05-17
Revised : 2013-06-24

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	VDSS	ID = 1 mA, VGS = 0	30			V
Drain-source cutoff current	IDSS	VDS = 30 V, VGS = 0			1.0	μA
Gate-source cutoff current	IGSS	VGS = ±10 V, VDS = 0			±10	μA
Gate threshold voltage	VTH	ID = 1.0 μA, VDS = 3.0 V	0.5	1.0	1.5	V
Drain-source on-state resistance	RDS(on)1	ID = 10 mA, VGS = 2.5 V		3	6	Ω
	RDS(on)2	ID = 10 mA, VGS = 4.0 V		2	3	Ω
Forward transfer admittance	|Yfs|	ID = 10 mA, VDS = 3.0 V	20	55		mS
Input capacitance	Ciss	VDS = 3 V, VGS = 0, f = 1 MHz		12		pF
Output capacitance	Coss			7		pF
Reverse transfer capacitance	Crss			3		pF
Turn-on time *1	ton	VDD = 3 V, VGS = 0 to 3 V RL = 300 Ω		100		ns
Turn-off time *1	toff	VDD = 3 V, VGS = 3 to 0 V RL = 300 Ω		100		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.
2. *1 Turn-on and Turn-off test circuit





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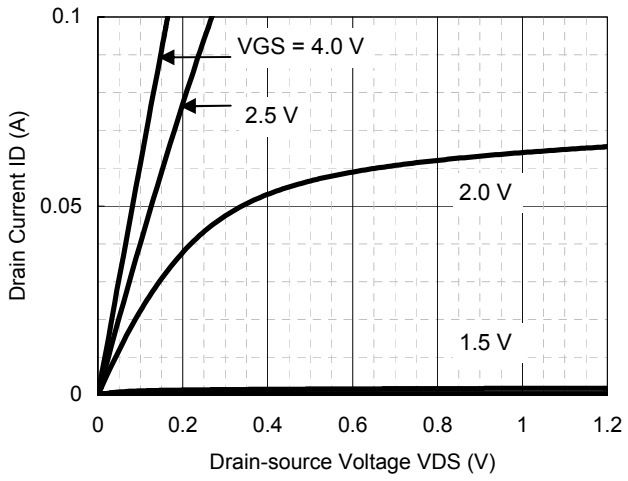
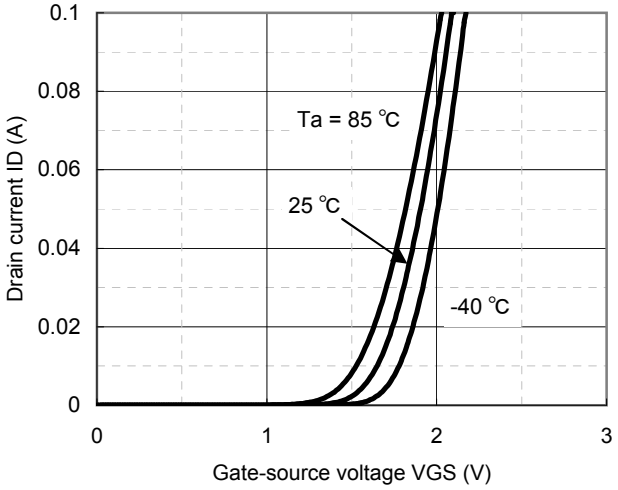
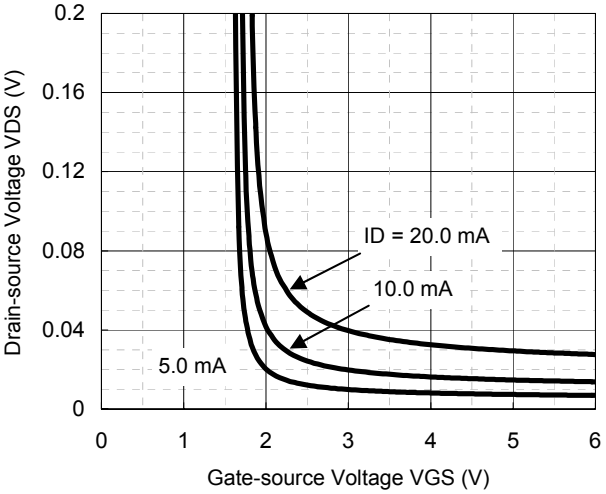
ID - VDS



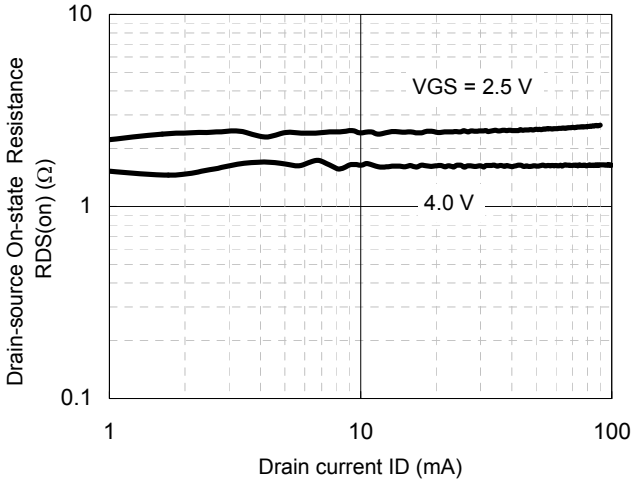
ID - VGS



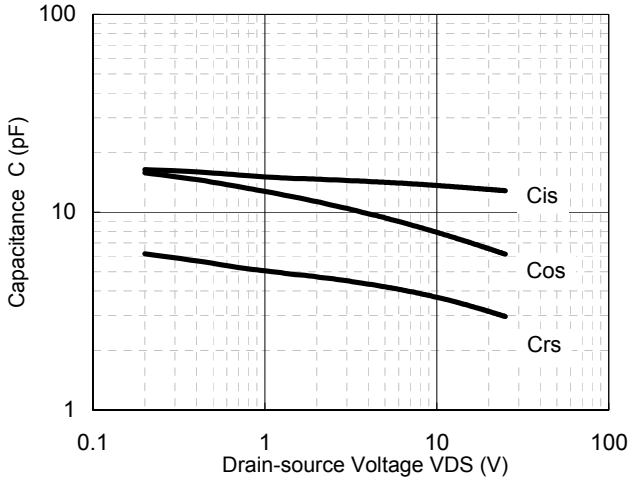
VDS - VGS



RDS(on) - ID



Capacitance - VDS



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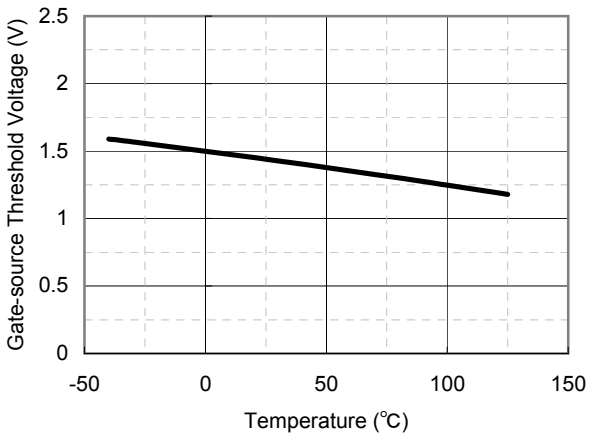
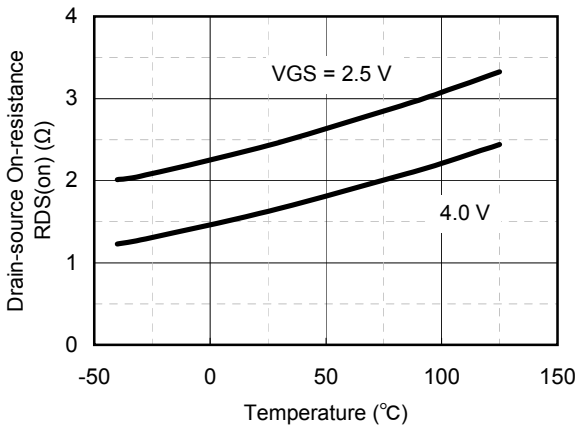
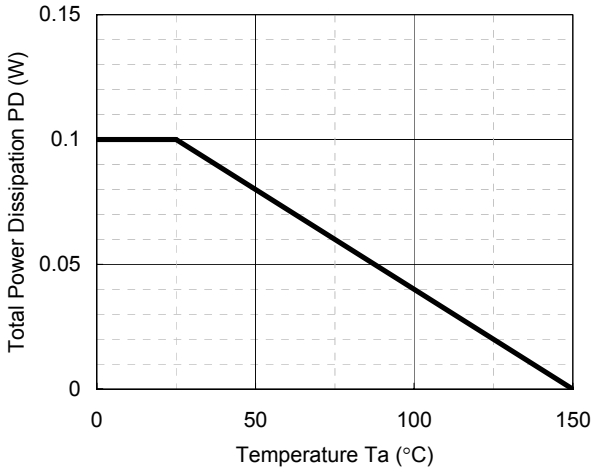
Vth - Ta



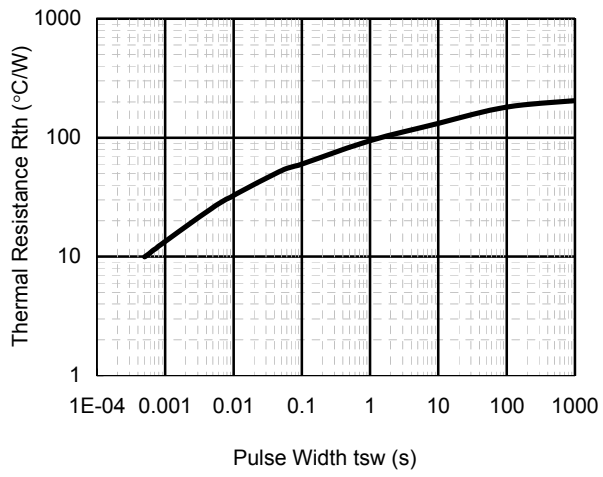
RDS(on) - Ta



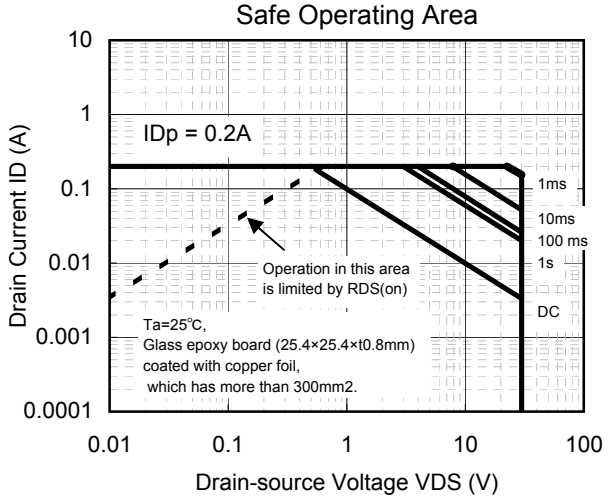
PD - Ta



Rth -tsw



Safe Operating Area



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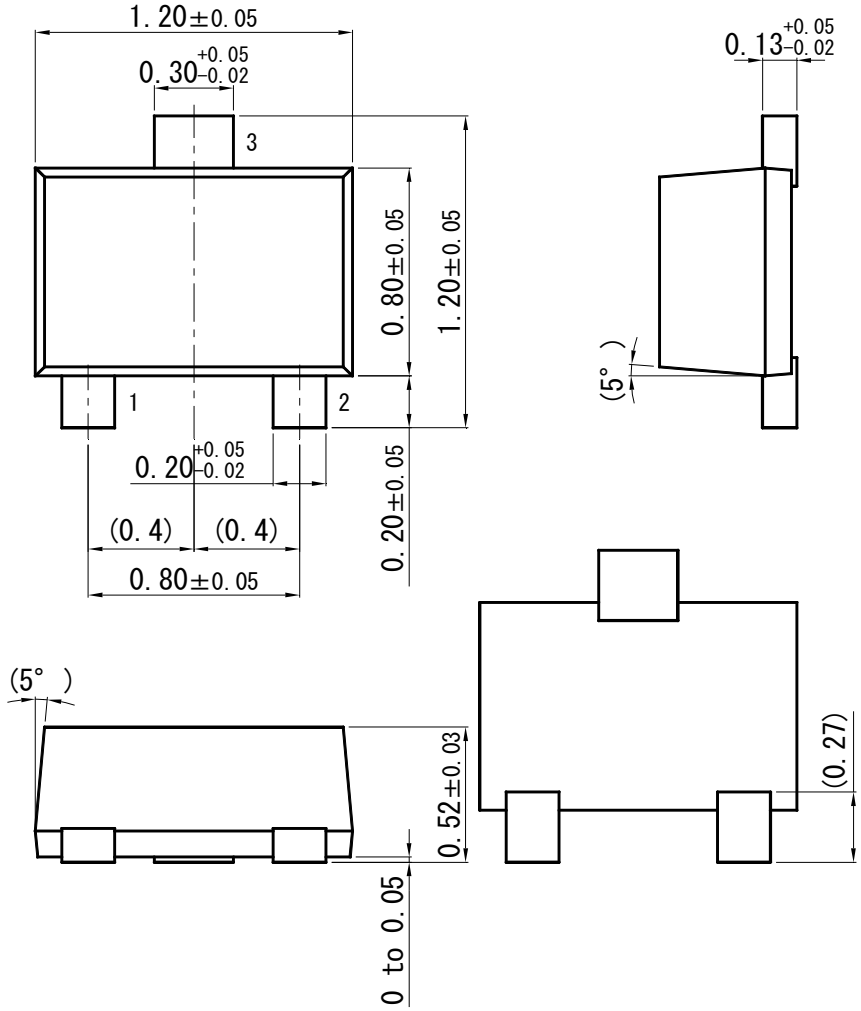
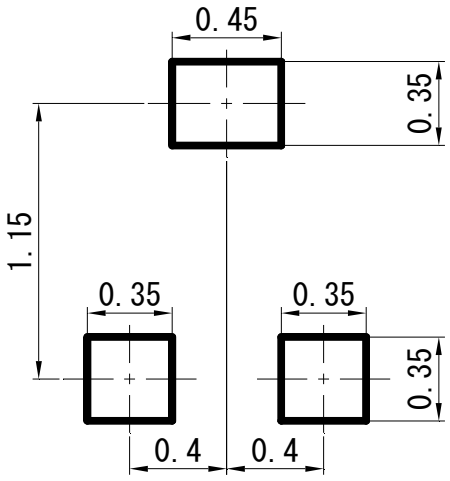
SSSMini3-F2-B

Unit : mm



■ Land Pattern (Reference) (Unit: mm)



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Request for your special attention and precautions in using the technical information and semiconductors described in this book

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